

P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY	
V _{DS} (V)	- 20
$R_{DS(on)}$ (m Ω) at V_{GS} = - 4.5 V	40
$R_{DS(on)}$ (m Ω) at V_{GS} = - 2.5 V	55
I _D (A)	- 6
Configuration	Single

FEATURES

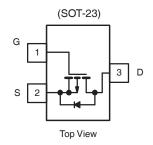
- DT-Trench Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

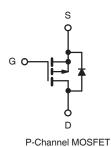


ROHS

APPLICATIONS

• Load Switch for Portable Devices





ABSOLUTE MAXIMUM RATING	S (T _C = 25 °C, unless	s otherwise noted	(k		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V_{DS}	- 20		
Gate-Source Voltage		V _{GS} ± 8			
Continuous Dunin Comment	T _C = 25 °C		- 6		
Continuous Drain Current	T _C = 75 °C	- I _D	- 5		
Continuous Source Current (Diode Conducti	ion)	I _S	- 3.5	Α	
Pulsed Drain Current ^a		I _{DM}	- 20		
Single Pulse Avalanche Current	1 0411	I _{AS}	- 12		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	6	mJ	
Maximum Dayyar Dissinations	T _C = 25 °C	2	W		
Maximum Power Dissipation ^a	T _C = 75 °C	P_{D}	0.8	VV	
Operating Junction and Storage Temperatur	re Range	T _J , T _{stq}	- 55 to + 150	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^b	R_{thJA}	175	°C/W
Junction-to-Foot (Drain)		R _{thJF}	75	G/ VV



PARAMETER	METER SYMBOL TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 20	-	-	V	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.45	-	- 2		
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	-	-	± 100	nA	
Zero Gate Voltage Drain Current	Inno	V _{GS} = 0 V, V _{DS} = - 20 V	-	-	- 1	· .	
	I _{DSS}	$V_{GS} = 0 \text{ V}, V_{DS} = -12 \text{ V}, T_{J} = 55 \text{ °C}$	-	-	- 10		
On-State Drain Current ^a	I _{D(on)}	$V_{GS} = -4.5 \text{ V}, \ V_{DS} \le -5 \text{ V}$	- 6	-	-	Α	
Drain-Source On-State Resistance ^a	P-ac.	$V_{GS} = -4.5 \text{ V}, I_D = -3 \text{ A}$	-	40	48	mΩ	
	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 2 A	-	55	70		
Forward Transconductance ^b	9fs	V _{DS} = - 5 V, I _D = - 3A	-	7	-	S	
Dynamic ^b							
Input Capacitance	C _{iss}		-	762	-	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = -10 \text{ V}, f = 1 \text{ MHz}$	-	444	-		
Reverse Transfer Capacitance	C _{rss}		-	350	-		
Total Gate Charge ^c	Qg		-	8.4	-		
Gate-Source Charge ^c	Q _{gs}	$V_{GS} = -4.5 \text{ V}, V_{DS} = -10 \text{ V}, I_{D} = -3 \text{ A}$	-	1		nC	
Gate-Drain Charge ^c	Q _{gd}		-	2.4			
Gate Resistance	R _g	f = 1 MHz	-	18.6	-	Ω	
Turn-On Delay Time ^c	t _{d(on)}		-	17	-		
Rise Time ^c	t _r	V_{DD} = - 6 V, R_L = 1.6 Ω I_D \cong - 3 A, V_{GEN} = - 4.5 V, R_g = 1 Ω	-	19	-	ns	
Turn-Off Delay Time ^c	t _{d(off)}		-	28	-		
Fall Time ^c	t _f		-	13	-		
Source-Drain Diode Ratings and Char-	acteristics ^b						
Pulsed Current ^a	I _{SM}		-	-	- 20	А	
Forward Voltage	V _{SD}	I _E = - 1 A, V _{GS} = 0 V	_	- 0.7	- 1.2	V	

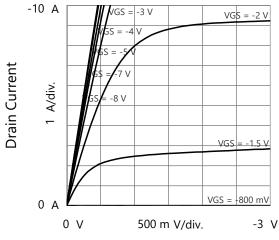
Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

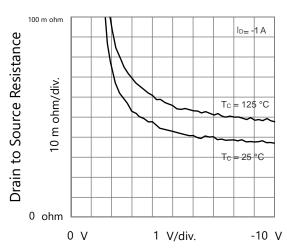
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



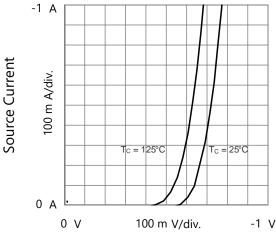
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



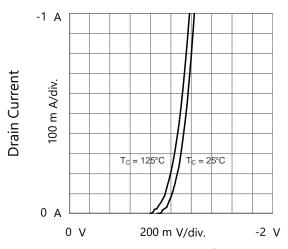
Drain to Source Voltage Output Characteristics



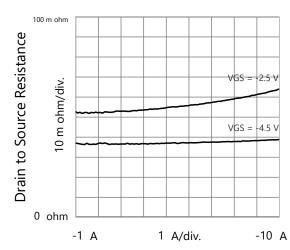
Gate to Source Voltage
Drain to Source Resistance vs. Gate to Source Voltage



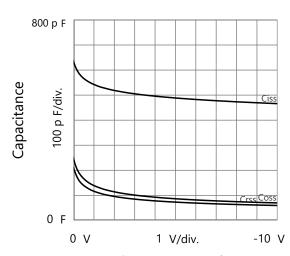
Source to Drain Voltage Body Diode Forward Characteristics



Gate to Source Voltage Transfer Characteristics



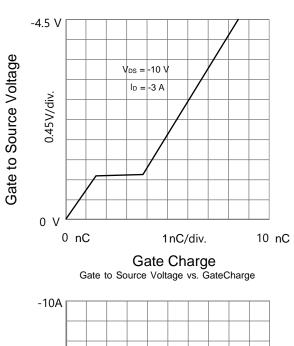
Drain Current
Drain to Source Resistance vs. Drain Current

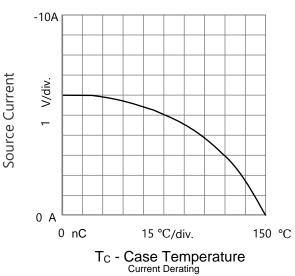


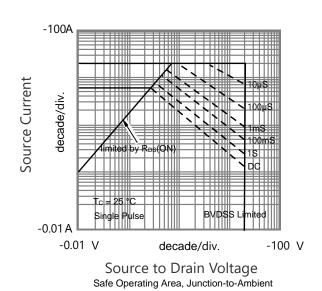
Drain to Source Voltage Capacitances

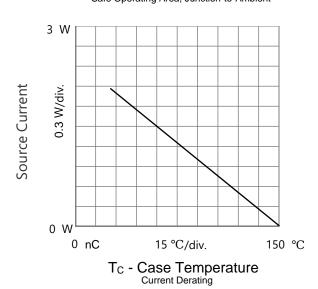


TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



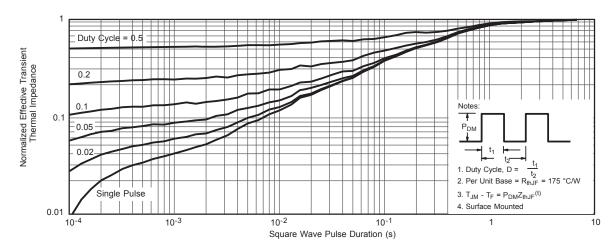








THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



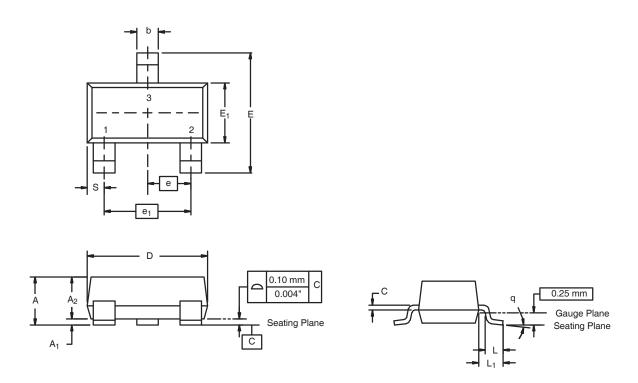
Normalized Thermal Transient Impedance, Junction-to-Foot

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



SOT-23: 3-LEAD

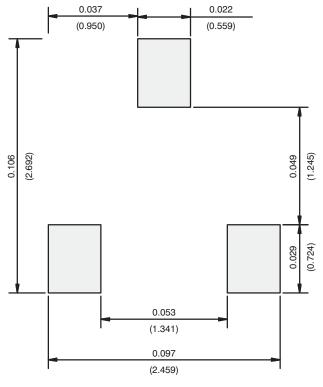


Dim -	MILLIM	IETERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020) Ref	
q	3°	8°	3°	8°	

DWG: 5479



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)





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